



General Description

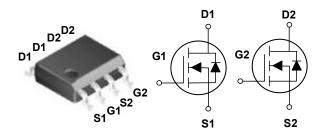
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
60 V	40 mΩ	4.5 A

Features

- $R_{DS(ON)} \leq 40 m\Omega @V_{GS} = 10V$
- · Improved dv/dt Capability
- Fast Switching
- · Green Device Available

SOP-8 Pin Configuration



Applications

- · Battery Powered System
- · Portable Equipment

Absolute Maximum Ratings T _J =25°C unless otherwise noted						
Symbol	Parameter	Rating	Units			
V_{DS}	Drain-Source Voltage	60	V			
V_{GS}	Gate-Source Voltage	±20	V			
I _D	Drain Current - Continuous (T _A =25°C)	4.5	Α			
I _{DM}	Drain Current - Pulsed (NOTE 1) (T _A =25°C)	11	Α			
EAS	Single Pulse Avalanche Energy (L=0.1mH)	6	mJ			
IAS	Single Pulse Avalanched Current (L=0.1mH)	11	Α			
P_{D}	Power Dissipation (T _A =25°C)	1.5	W			
T_J	Operating Junction Temperature Range	-50 to 150	°C			
T _{STG}	Storage Temperature Range	-50 to 150	°C			
Marking Code		NG040				

Thermal Characteristics					
Symbol Parameter		Тур.	Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		85	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =48V , V_{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
RDOVONI	Static Drain-Source On-Resistance	V_{GS} =10V , I_D =6A			40	mΩ
	(NOTE 2)	V _{GS} =4.5V , I _D =5.5A			47	11122
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.2	1.8	2.5	V
gfs	Forward Transconductance	V_{DS} =5V , I_{D} =3A		10		S

Dynamic and switching Characteristics (NOTE 3)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			26		
Q_gs	Gate-Source Charge	V_{DS} =30V , V_{GS} =10V , I_{D} =6A		4		nC
Q_{gd}	Gate-Drain Charge			4.8		
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=30V , V_{GS}=10V , R_{GEN}=6\Omega ,$ $I_{D}=1A$		6.2		
T _r	Rise Time			22		nS
$T_{d(off)}$	Turn-Off Delay Time			45		113
T_f	Fall Time			21		
C _{iss}	Input Capacitance	V _{DS} =30V , V _{GS} =0V , F=1MHz		1108		
C _{oss}	Output Capacitance			60		pF
C_{rss}	Reverse Transfer Capacitance			43		
Rg	Gate resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		3.8		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V_{SD}	Diode Forward Voltage (NOTE 2)	V_{GS} =0V , I_{S} =3A			1.1	V
t _{rr}	Reverse Recovery Time	V _R =0V , I _F =3A , dI/dt=100A/us		20		nS
Q_{rr}	Reverse Recovery Charge			16		nC

NOTES:

- 1. Max. current is limited by junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Guaranteed by design, not subject to production testing.



S8MNG040



60V Dual N-Channel MOSFETs

Characteristics Curves

FIG. 1-Drain Current

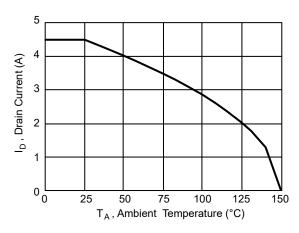


FIG. 2-Normalized $R_{DS(ON)}$ vs. T_J

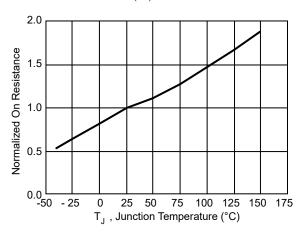


FIG. 3-Normalized V_{th} vs. T_J

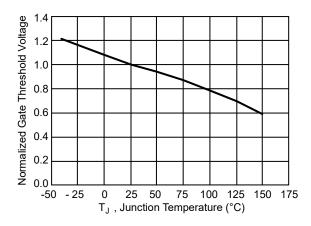


FIG. 4-Gate Charge Characteristics

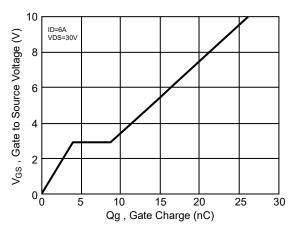


FIG. 5-R $_{\theta JA}$ Transient Thermal Impedance

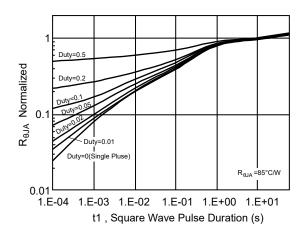
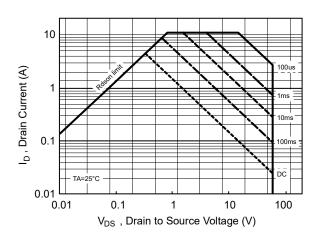


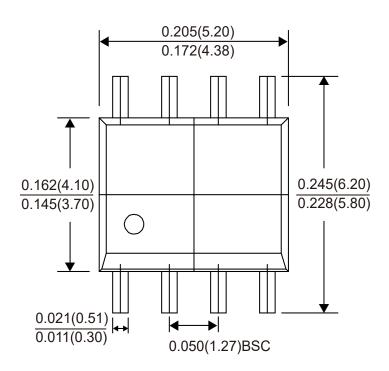
FIG. 6-Safe Operation Area

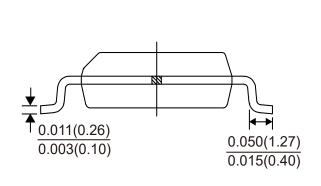


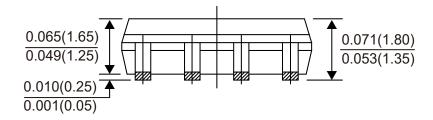




Package Outline Dimensions







SOP-8Dimensions in inches and (millimeters)





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